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Printed Board Handling and Storage Guidelines

Supersedes IPC-1601
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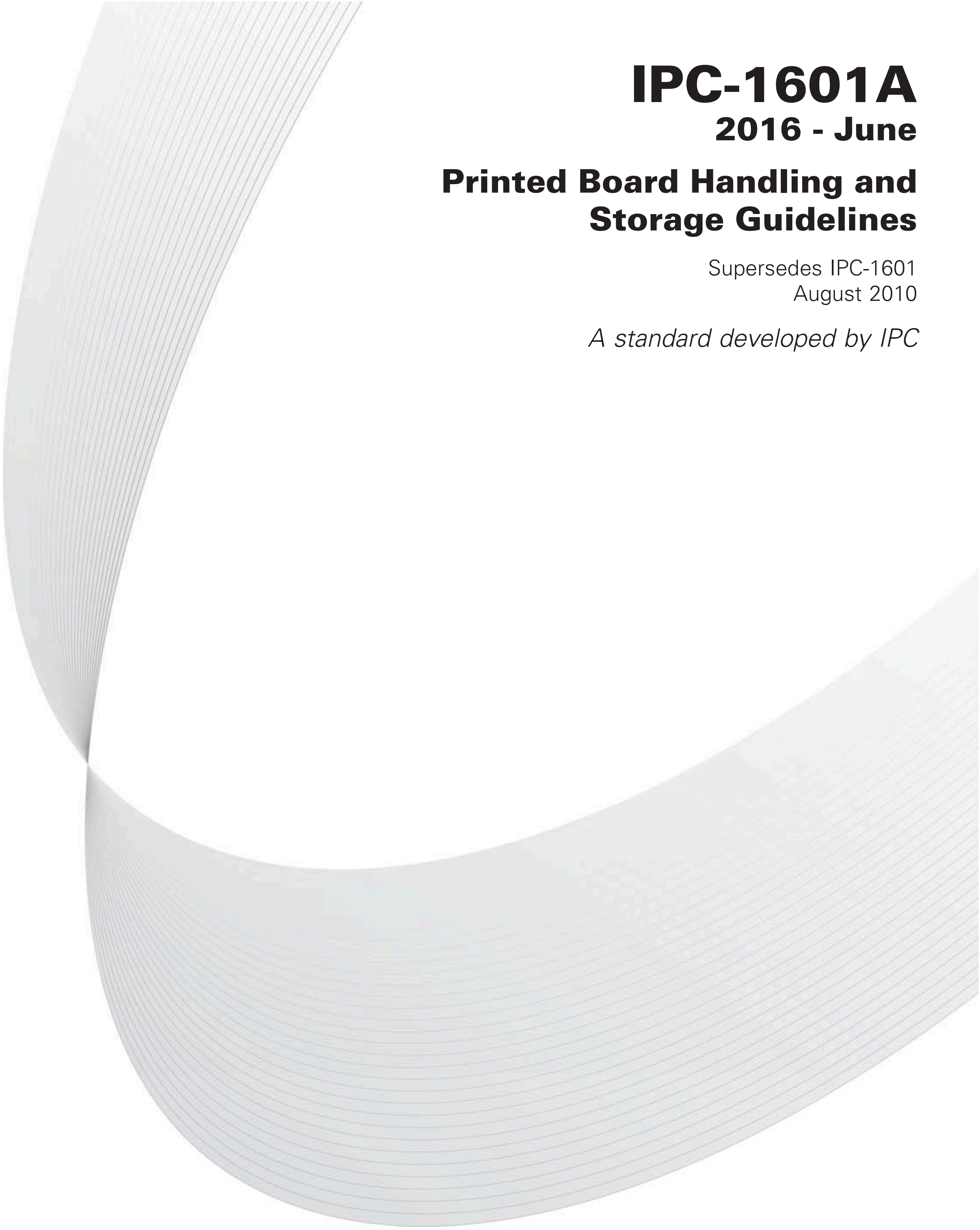
A standard developed by IPC



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Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Thank you for your continued support.

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Printed Board Handling and Storage Guidelines

Developed by the Printed Board Storage and Handling Subcommittee (D-35) of the Rigid Printed Board Committee (D-30) of IPC

Supersedes:
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Users of this publication are encouraged to participate in the development of future revisions.

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Acknowledgment

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Rigid Printed Board Committee	Printed Board Storage and Handling Subcommittee	Technical Liaison of the IPC Board of Directors
Chair Debora L. Obitz National Technical Systems Anaheim	Chair Joseph E. Kane BAE Systems Platform Solutions	Bob Neves Microtek (Changzhou) Laboratories
Vice-Chair Clifford R. Maddox Boeing Company	Vice-Chair Don Dupriest Lockheed Martin Missiles & Fire Control	

Printed Board Storage and Handling Subcommittee

Lance A. Auer, Raytheon Missile Systems

Erik Bjerke, BAE Systems

Wendi Boger, TTM Technologies

Scott A. Bowles, L-3 Fuzing and Ordnance Systems, Cincinnati

Denise Chevalier, Amphenol Printed Circuits, Inc.

Beverley Christian, University of Maryland

Michael A. Collier, Teledyne Printed Circuit Technologies

Kelly M. Daniluk, NASA Goddard Space Flight Center

Harold O. Ellison, Quantum Corporation

Gary M. Ferrari, FTG Circuits

Tim Gallagher, BAE Systems

Michael J. Gay, Isola Group

Cynthia A. Gomez, Continental Temic SA de CV

Constantino J. Gonzalez, ACME Training & Consulting

Vicka Hammill, Honeywell Inc. Air Transport Systems

Philip M. Henault, Raytheon Company

Gaston Hidalgo, Samsung Electronics America

Mike Hill, TTM Technologies

David D. Hillman, Rockwell Collins

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Clifford R. Maddox, Boeing Company

Brian D. Madsen, Continental Automotive Systems

Israel Martinez Montano, Continental Automotive Nogales S.A. de C.V.

Matthew T. McQueen, NSWC Crane

Peter B. Menuez, L-3 Communications - Cincinnati Electronics

Steven M. Nolan, Lockheed Martin Mission Systems & Training

Russell H. Nowland, Nokia

Gerard O'Brien, Solderability Testing & Solutions, Inc.

Agnieszka Ozarowski, BAE Systems

Gerry Partida, Marcel Electronics International

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Douglas R. Schueller, AbelConn, LLC

Jose M. Servin Olivares, Continental Temic SA de CV

Bhanu Sood, NASA Goddard Space Flight Center

Rainer Taube, Taube Electronic GmbH

Juan F. Vasquez, TTM Technologies

Michael K. Weinhold, PLUS Leiterplatten G